

**NPN medium power transistor****BCP68****FEATURES**

- High current (max. 1 A)
- Low voltage (max. 20 V).

**APPLICATIONS**

- General purpose switching and amplification under high current conditions.

**DESCRIPTION**

NPN medium power transistor in a SOT223 plastic package. PNP complement: BCP69.

**PINNING**

PIN	DESCRIPTION
1	base
2, 4	collector
3	emitter

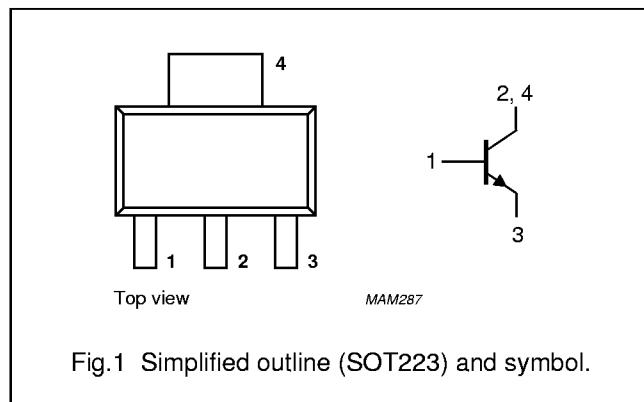


Fig.1 Simplified outline (SOT223) and symbol.

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	–	32	V
$V_{CEO}$	collector-emitter voltage	open base	–	20	V
$V_{EBO}$	emitter-base voltage	open collector	–	5	V
$I_C$	collector current (DC)		–	1	A
$I_{CM}$	peak collector current		–	2	A
$I_{BM}$	peak base current		–	200	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25^\circ\text{C}$ ; note 1	–	1.37	W
$T_{stg}$	storage temperature		-65	+150	$^\circ\text{C}$
$T_j$	junction temperature		–	150	$^\circ\text{C}$
$T_{amb}$	operating ambient temperature		-65	+150	$^\circ\text{C}$

**Note**

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm<sup>2</sup>. For other mounting conditions, see "Thermal considerations for SOT223 in the General Part of associated Handbook".

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BCP68

**THERMAL CHARACTERISTICS**

<b>SYMBOL</b>	<b>PARAMETER</b>	<b>CONDITIONS</b>	<b>VALUE</b>	<b>UNIT</b>
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	91	K/W
$R_{th\ j-s}$	thermal resistance from junction to soldering point		10	K/W

**Note**

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm<sup>2</sup>.  
For other mounting conditions, see "Thermal considerations for SOT223 in the General Part of associated Handbook".

**CHARACTERISTICS** $T_j = 25^\circ\text{C}$  unless otherwise specified.

<b>SYMBOL</b>	<b>PARAMETER</b>	<b>CONDITIONS</b>	<b>MIN.</b>	<b>TYP.</b>	<b>MAX.</b>	<b>UNIT</b>
$I_{CBO}$	collector cut-off current	$I_E = 0; V_{CB} = 25\text{ V}$	—	—	100	nA
		$I_E = 0; V_{CB} = 25\text{ V}; T_j = 150^\circ\text{C}$	—	—	10	$\mu\text{A}$
$I_{EBO}$	emitter cut-off current	$I_C = 0; V_{EB} = 5\text{ V}$	—	—	100	nA
$h_{FE}$	DC current gain	$I_C = 5\text{ mA}; V_{CE} = 10\text{ V}$	50	—	—	
		$I_C = 500\text{ mA}; V_{CE} = 1\text{ V};$ see Fig.2	85	—	375	
		$I_C = 1\text{ A}; V_{CE} = 1\text{ V};$ see Fig.2	60	—	—	
	DC current gain BCP68-25	$I_C = 500\text{ mA}; V_{CE} = 1\text{ V};$ see Fig.2	160	—	375	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 1\text{ A}; I_B = 100\text{ mA}$	—	—	500	mV
$V_{BE}$	base-emitter voltage	$I_C = 5\text{ mA}; V_{CE} = 10\text{ V}$	—	620	—	mV
		$I_C = 1\text{ A}; V_{CE} = 1\text{ V}$	—	—	1	V
$C_c$	collector capacitance	$I_E = i_e = 0; V_{CB} = 5\text{ V}; f = 1\text{ MHz}$	—	38	—	pF
$f_T$	transition frequency	$I_C = 10\text{ mA}; V_{CE} = 5\text{ V}; f = 100\text{ MHz}$	40	—	—	MHz
$\frac{h_{FE1}}{h_{FE2}}$	DC current gain ratio of the complementary pairs	$ I_C  = 0.5\text{ A};  V_{CE}  = 1\text{ V}$	—	—	1.6	

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BCP68

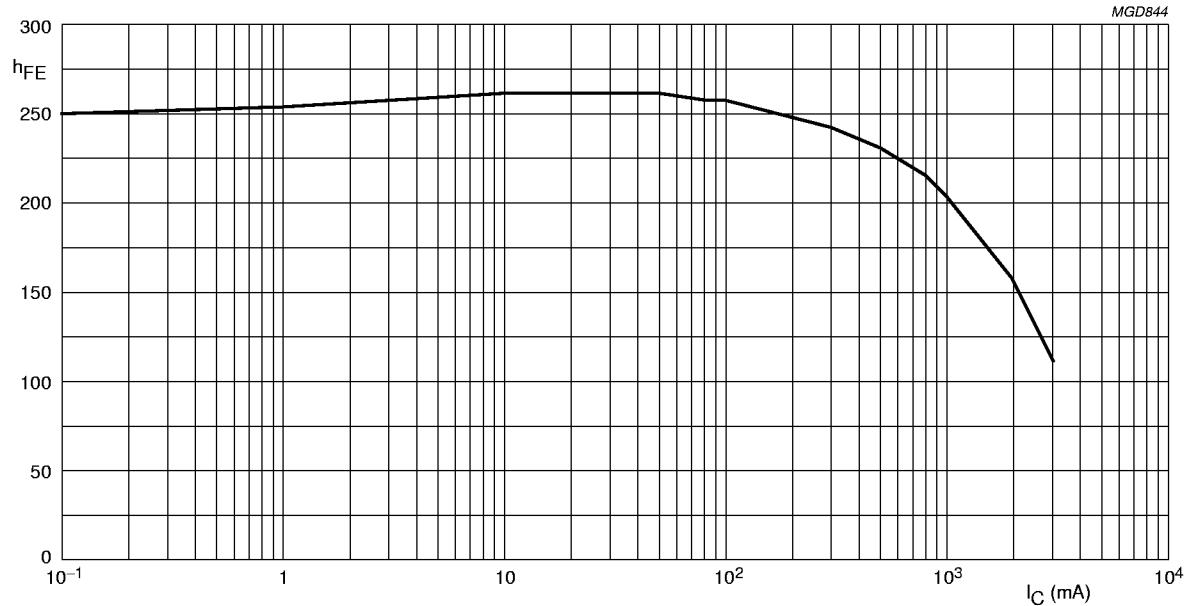
 $V_{CE} = 1$  V.

Fig.2 DC current gain; typical values.

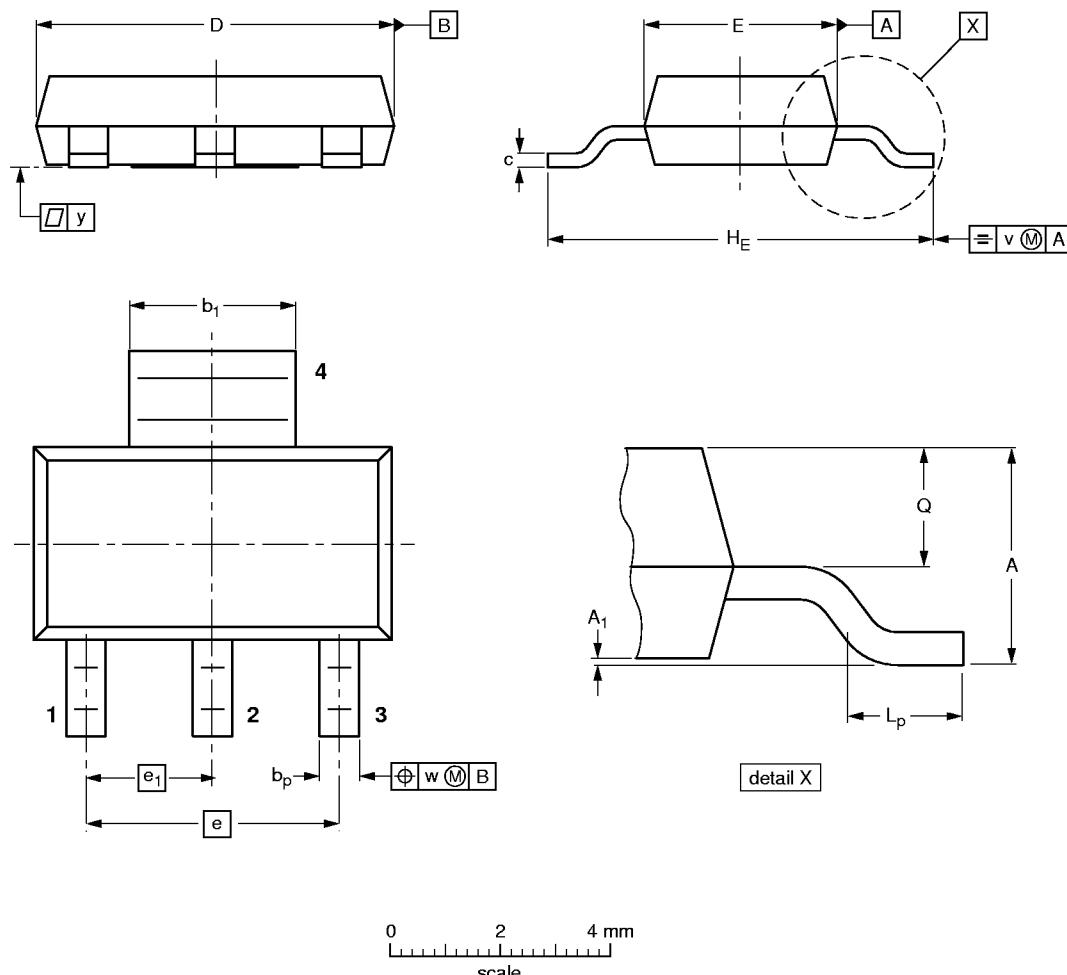
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BCP68

## PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



## DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	b <sub>p</sub>	b <sub>1</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w	y
mm	1.8	0.10	0.80	3.1	0.32	6.7	3.7	4.6	2.3	7.3	1.1	0.95	0.2	0.1	0.1
	1.5	0.01	0.60	2.9	0.22	6.3	3.3			6.7	0.7	0.85			

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT223						96-11-11 97-02-28